A METHOD OF PERFORMING BACK-END MANUFACTURING OF AN INTEGRATED CIRCUIT DEVICE

ABSTRACT OF THE DISCLOSURE

A method of performing back-end manufacturing of an integrated circuit (IC) device is disclosed. In one method embodiment, the present invention processes a die-strip through a front-of-line assembly portion which comprises a plurality of sub-stations operating on an in-line basis. The die-strip is then automatically provided to an end-of-line assembly portion. The die-strip is then processed through an end-of-line assembly portion which comprises a plurality of sub-stations operating on an in-line basis. The present embodiment then automatically provides the die-strip to a test assembly portion. The die-strip is then tested by the test portion and then automatically provided to a finish assembly portion. The present embodiment then processes the die-strip through a finish portion which comprises a plurality of sub-stations operating on an in-line basis. Camera systems perform automated visual inspection of dies on the die-strip and maintain a database that can be used for automated reject management.